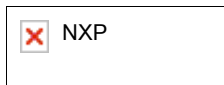


Pcn System

From: noreply.businessservices@nxp.com
Sent: Monday, February 04, 2013 2:08 PM
To: Pcn System
Subject: NXP Quality - 201209032F01W - Final Product Change Notification



Final Product Change Notification 201209032F01W

Issue Date: 31-Jan-2013
Effective Date: 01-Feb-2013

WITHDRAWN

Dear *Pcn System2*,

Here's your personalized quality information concerning products Future Electronics purchased from NXP.

For detailed information we invite you to [view this notification online](#)



Management Summary

Transfer remaining production of DIP packages from APB to subcontractor Vigilant at Bangkok, Thailand (Phase 5).

Change Category

- | | | | |
|--|--|---|--|
| <input type="checkbox"/> Wafer Fab process | <input checked="" type="checkbox"/> Assembly Process | <input checked="" type="checkbox"/> Product Marking | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specificatio |
| <input type="checkbox"/> Wafer Fab location | <input checked="" type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input type="checkbox"/> Packing/Shipping/Labeling |

Transfer remaining DIP packages from APB to Vigilant at Bangkok Thailand (phase 5)

Details of this Change

Transfer remaining production of DIP packages from APB (NXP Semiconductors Assembly Plant Bangkok Thailand) to subcontractor VGT (Vigilant Technology Co., Ltd. Bangkok Thailand).

NXP will transfer all remaining production / product types in DIP packages from the in house assembly APB (Bangkok) to the subcontractor Vigilant (Bangkok).

This transfer will include:

- Transfer of dedicated equipment / tooling from APB to Vigilant.
- After transfer the transferred products will be assembly at Vigilant, partly on former APB equipment and with Vigilant personnel.
- A change of Bill of Materials to standardize to Vigilant BoM.
- The final test location will not change, this will stay at APB.

This change will be communicate through several customer communications (PCNs) in parallel.

This specific PCN communicates the transfer of product types using pre-plated leadframes (PPF).

For all products in this PCN the die attach material and for some of the products the mould compound materials will change to the standard Vigilant BoM:

- Die attach material to standardize from 71-1D and EP121-7 to 2200D.
- Mould compound material to standardize from EME6210 and MP-47MX to MP-74MX for all.

Why do we Implement this Change

The production volume of the DIP packages in our Bangkok assembly center is decreasing, as the usage of these product outlines in the market passed maturity. In response it has been decided to transfer our DIP assembly to our subcontractor Vigilant, to have a third party with sufficient load to maintain these DIP assembly lines.

Identification of Affected Products

Packages can be identified by the assembly code that is marked on the 3rd line "C" of the top-side product marking:

NXP Semiconductors Bangkok Thailand (APB) = code "n".
Vigilant Bangkok = code "+".

Product Availability

Sample Information

Samples are available upon request

For sample request, please respond to email address str.logic.nym@nxp.com

Production

Planned first shipment 29-Jan-2013

Withdrawal Information

NXP has decided to cancel the transfer of DIP production from APB to Vigilant because of revised allocation strategy. All production of product types in these DIP packages will remain at APB until further notice.

Impact

No impact on form, fit, function, quality, reliability and manufacturability anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information: see attached file

Self qualification: [view online](#)

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 02-Mar-2013.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Emile Busink
Position	QA engineering Logic / MCU
e-mail address	emile.busink@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications. A global semiconductor company with operations in more than 25 countries, NXP posted revenue of \$4.4 billion in 2010.

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